

3M™ Textool™ BGA Test & Burn-In Sockets

1.00 mm, Types 0, I, II and III Open Top



- Double-beam normally-closed contact delivers balanced, opposing forces to solder ball with minimal shear stress
- Contact tips touch ball above its center plane producing only slight indentations and minimal ball deformation
- Allows excellent air flow around device
- Includes a retractable locating guide for easy board mounting even with hundreds of leads
- Compatible with most robotic handlers while it provides easy manual operation
- Accepts package body sizes up to 29 mm square with a maximum matrix of 27 x 27
- RoHS* compliant

Date Modified: June 16, 2005

TS-9300-08
Sheet 1 of 5

Physical

Body Material:	Polyethersulfone (PES)
Flammability:	UL 94V-0
Color:	Black
Alignment Plate Material:	Liquid Crystal Polymer (LCP)
Flammability:	UL 94V-0
Color:	Black
Contact Material:	Beryllium Copper
Plating:	30µ" (0.76 µm) Gold over 50µ" (1.3 µm) Nickel
Other Metal Parts:	Stainless Steel

Electrical

Insulation Resistance:	>1000MΩ at 500 Vdc
Withstanding Voltage:	500 Vrms at sea level
Initial Contact Resistance:	<50mΩ measured at 1.0 mA applied current
Current Rating:	1.0 A max @ 25°C

Environmental

Operating Temperature Rating: -55°C to +150°C

Mechanical

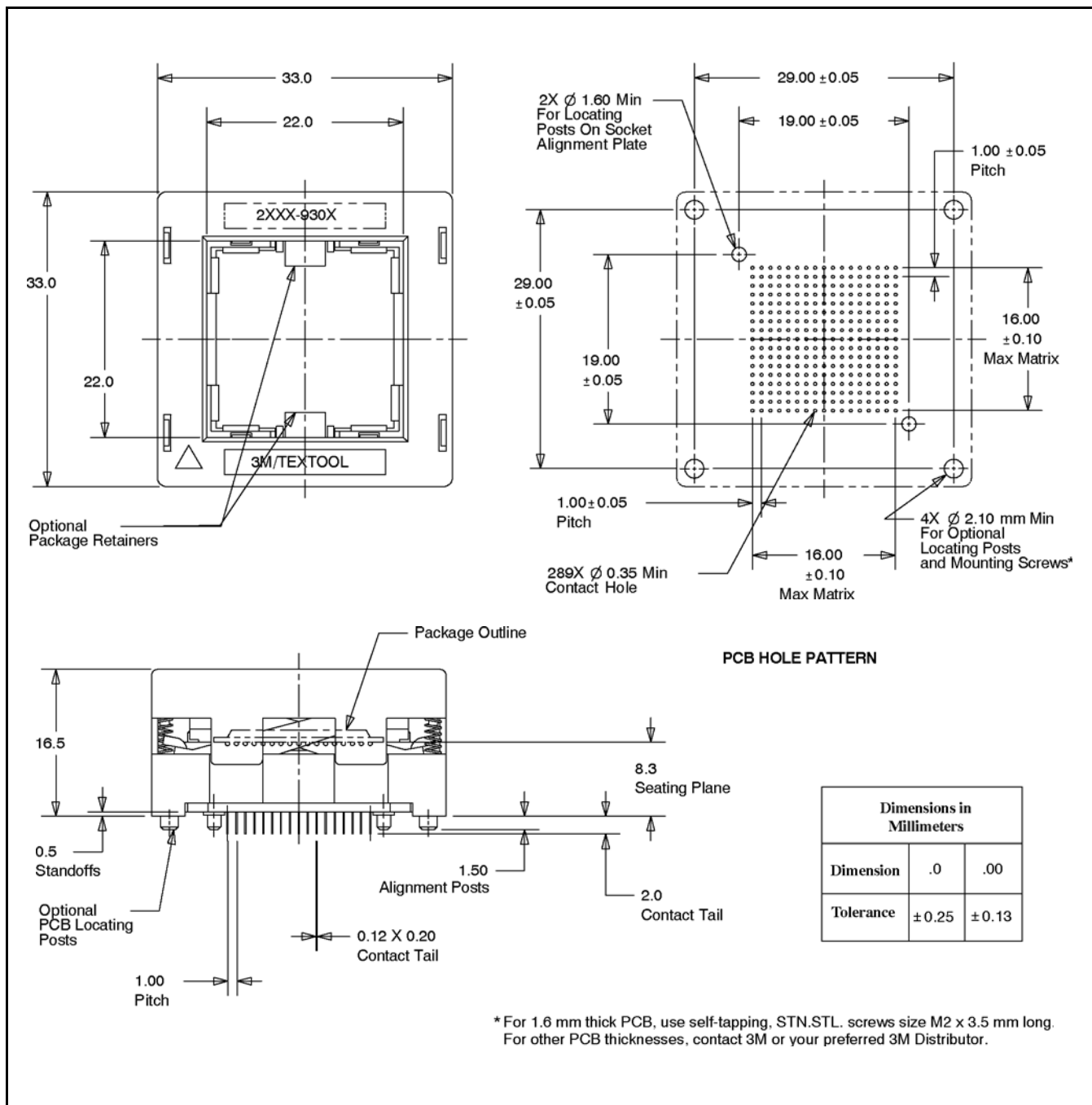
Durability:	20,000 actuations (10,000 devices load/unload) at room temperature
Initial Contact Force:	17 gf (0.17N) Nom for 0.6 mm diameter solder ball 14 gf (0.14N) Nom for 0.5 mm diameter solder ball
Initial Actuation Force:	Type II-5Kgf @ full pin count
Contact Wiper Gap - Fully Open:	0.85 mm Nom

* RoHS = Directive 2002/95/EC, Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment
"RoHS compliant" means that the product or part does not contain any of the following substances in excess of the following maximum concentration values in any homogeneous material, unless the substance is in an application that is exempt under RoHS: (a) 0.1% (by weight) for lead, mercury, hexavalent chromium, polybrominated biphenyls or polybrominated diphenyl ethers; or (b) 0.01% (by weight) for cadmium. Unless otherwise stated by 3M in writing, this information represents 3M's knowledge and belief based upon information provided by third party suppliers to 3M.

3M™ Textool™ BGA Test & Burn-In Sockets

1.00 mm, Types 0, I, II and III Open Top

Type 0



Package Specifications

Max Package Size: 19.0 mm ± 0.1 mm SQ Max

Max Matrix: 17 × 17

Ball Diameter: 0.40 mm - 0.70 mm

Ball Height: 0.40 mm Min

P.C.B. Recommendations

Board Thickness: 1.6 mm

Through Hole Diameter 0.35 mm Min

TS-9300-08
Sheet 2 of 5



Interconnect Solutions

<http://www.3M.com/interconnects/>

3M and Textool are trademarks of 3M Company.

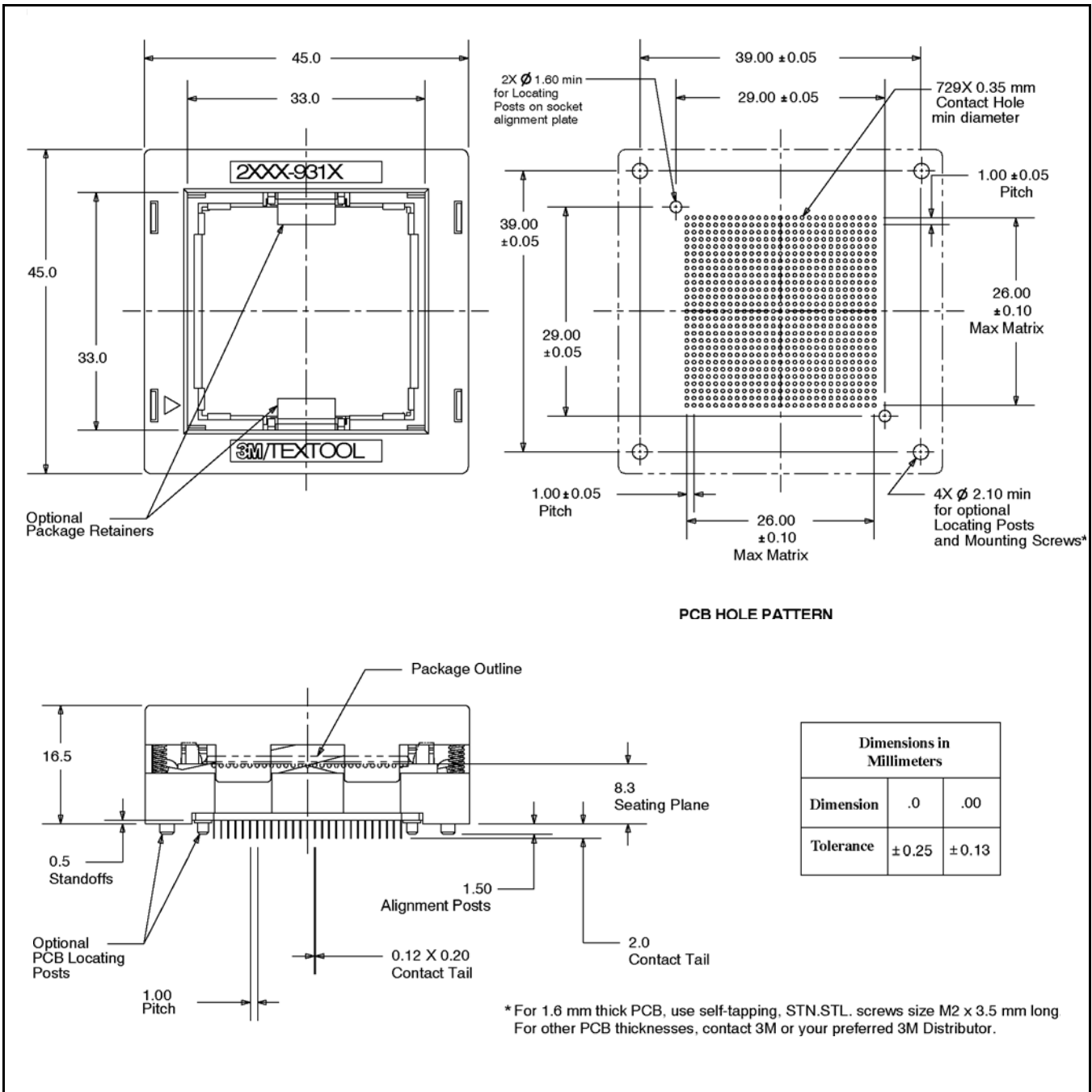
For technical, sales or ordering information call

800-225-5373

3M™ Textool™ BGA Test & Burn-In Sockets

1.00 mm, Types 0, I, II and III Open Top

Type I



Package Specifications

Max Package Size: 29 mm ± 0.1 mm SQ Max

Max Matrix: 27 × 27 Max

Ball Diameter: 0.40 mm - 0.70 mm

Ball Height: 0.40 mm Min

P.C.B. Recommendations

Board Thickness: 1.6 mm

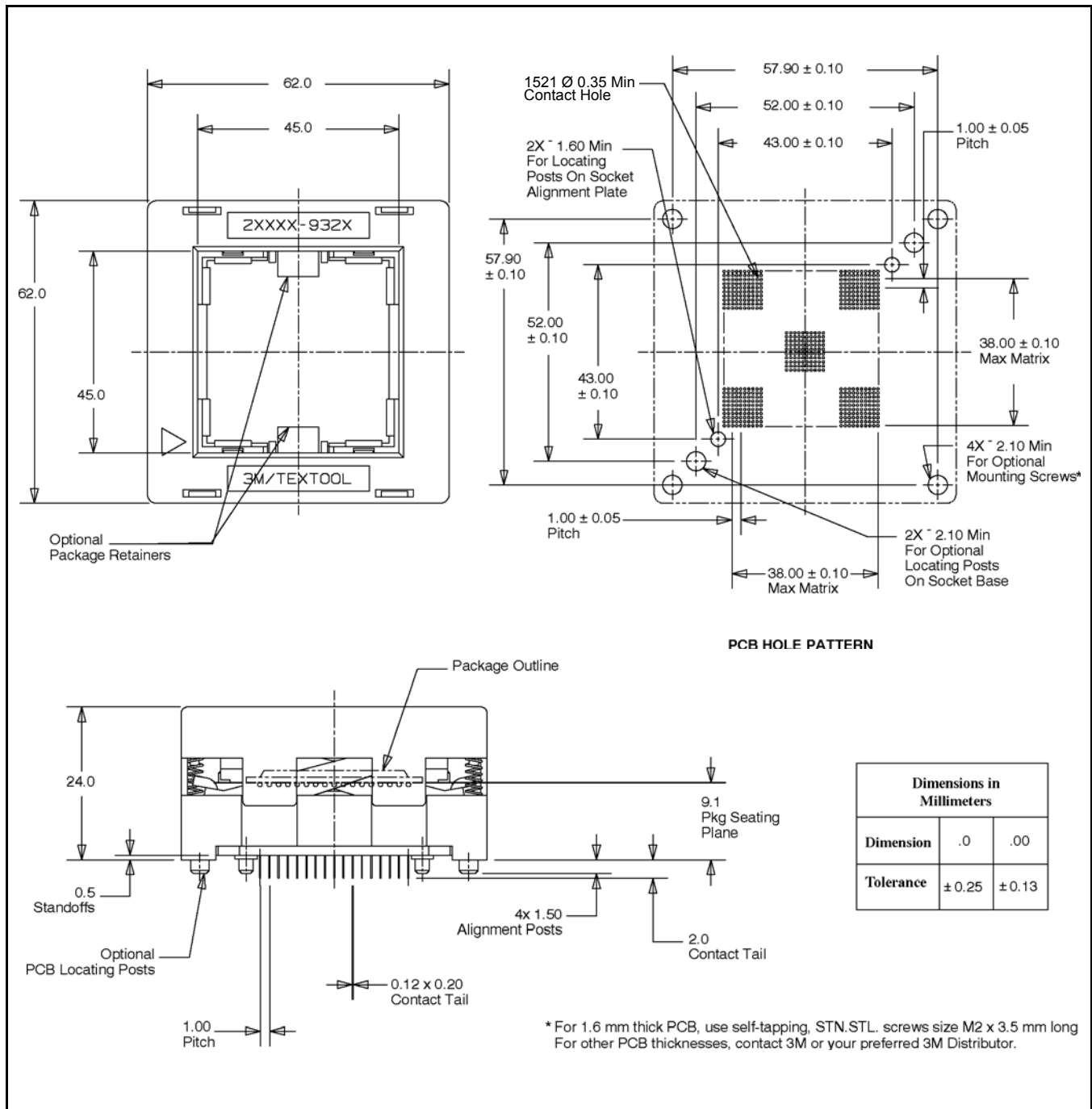
Through Hole Diameter 0.35 mm Min

TS-9300-08
Sheet 3 of 5

3M™ Textool™ BGA Test & Burn-In Sockets

1.00 mm, Types 0, I, II and III Open Top

Type II



Package Specifications

Max Package Size: 40.0 mm ± 0.1 mm SQ Max

Max Matrix: 39 × 39

Ball Diameter: 0.40 mm - 0.70 mm

Ball Height: 0.40 mm Min

P.C.B. Recommendations

Board Thickness: 1.6 mm

Through Hole Diameter 0.35 mm Min

TS-9300-08
Sheet 4 of 5



Interconnect Solutions

<http://www.3M.com/interconnects/>

3M and Textool are trademarks of 3M Company.

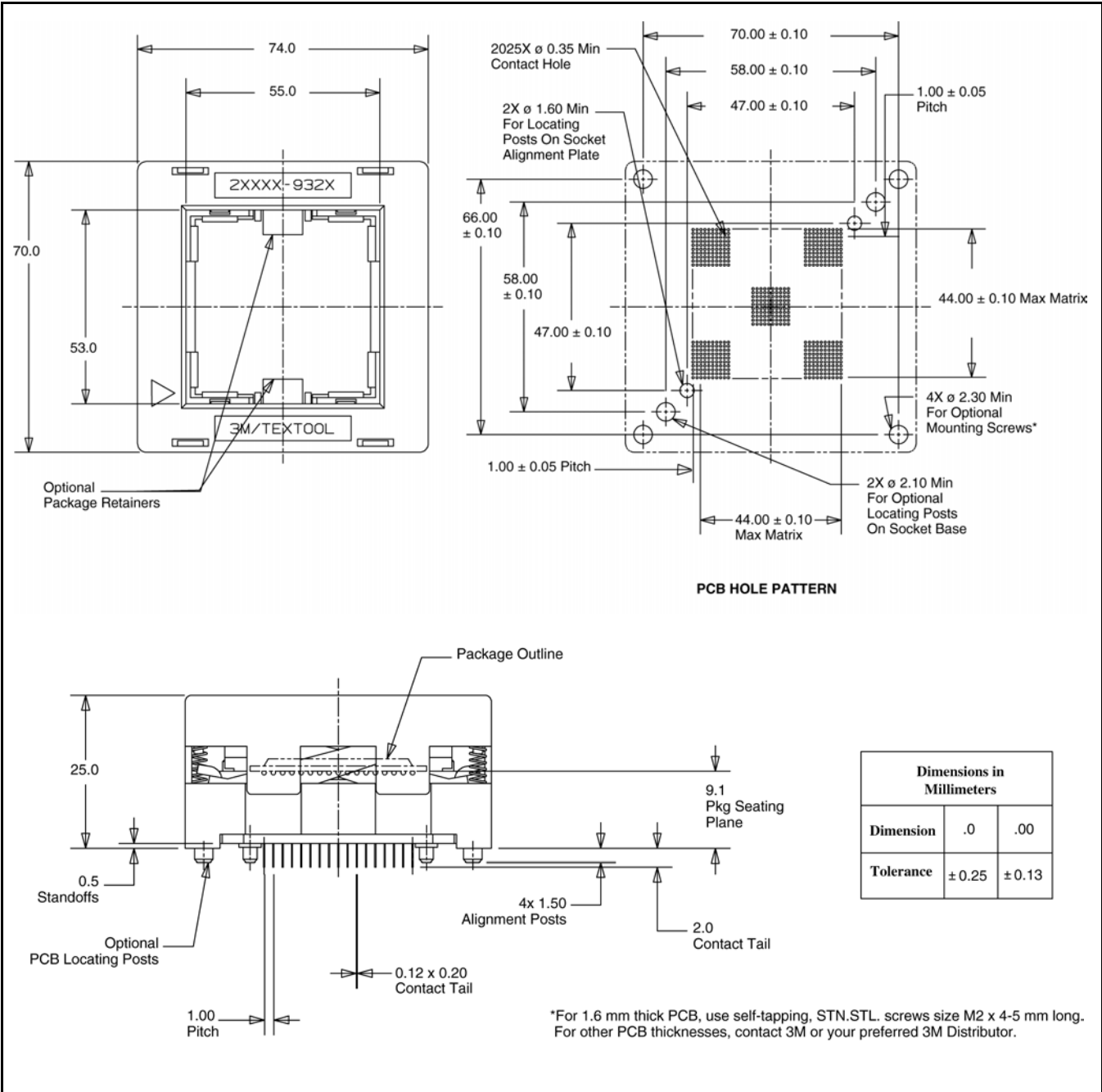
For technical, sales or ordering information call

800-225-5373

3M™ Textool™ BGA Test & Burn-In Sockets

1.00 mm, Types 0, I, II and III Open Top

Type III



Package Specifications

Max Package Size: 47.5 mm ± 0.1 mm SQ Max

Max Matrix: 45 × 45

Ball Diameter: 0.50 mm - 0.70 mm

Ball Height: 0.40 mm Min

P.C.B. Recommendations

Board Thickness: 1.6 mm

Through Hole Diameter 0.35 mm Min

TS-9300-08
Sheet 5 of 5